

Imaging Solutions

Code Information

- **MOS**
- **CIS**
- **CCD**

August 2009

MOS Code Information(1/2)

Last Updated : August 2009

S 5 X X X X X X X X - X X X X
 1 2 3 4 5 6 7 8 9 10 11 12 13 14 15

1. System LSI (S)

2. Large Classification : MOS (5)

3. Small Classification

- A : Audio
- B : Analog Core
- C : Camera
- D : Display
- F : CCD
- G : General
- H : Home(Appliance) Video
- I : Digital Core
- K : CIS
- L : Optical
- M : Mobile Automation
- N : Network
- P : Processor
- S : SLINK(Serial Link)
- T : Telecom
- V : Process Vehicle
- W : Library
- X : MODULE(CAMERA MODULE)
- Y : Memory Card
- Z : Custom
- 2 : EEPROM
- 4 : DRAM CORE
- 6 : FLASH CORE

4~7.

Serial No

8. Version

A~Z

*1st Version → X

9~10. Mask Option

11. " - "

12. Package Type

- | | |
|-----------|--------------|
| 1 : TEBGA | 2 : MODULE |
| 3 : QFN | 4 : MLF |
| 5 : ELP2 | 6 : WFP |
| 7 : LPCC | 8 : FCBGA |
| 9 : PBGA | A : SDIP |
| B : BGA | C : CHIP BIZ |
| D : DIP | E : LQFP |
| F : BCC++ | G : ELQFP |
| H : ULGA | J : ELP |
| K : SBGA | L : FCFBGA |
| M : QFPH | N : PBGAH |
| P : PLCC | Q : QFP |
| R : TSSOP | S : SOP |
| T : TQFP | U : UELP |
| V : SSOP | W : WAFER |
| X : ETQFP | Y : FBGA |
| Z : STBGA | |

13. Reserved

- | | |
|------------------|------------------|
| 0 : none | 1 : PKG Option 1 |
| 2 : PKG Option 2 | 3 : PKG Option 3 |
| | |
| G : PKG Option G | H : PKG Option H |

14. Packing

- | | |
|------------------------------------|-----------------|
| B : Tube | U : Bulk |
| R : Tray | T : Tape & Reel |
| S : Tape & Reel Reverse | C : Chip Biz |
| D : Chip Biz (3 Inch tray) | |
| E : Chip Biz (4 Inch tray) | |
| F : Chip Biz (Reverse) | |
| W : WF Biz Draft Wafer | |
| X : WF Biz Full Cutting | |
| 3 : Tape & Reel (Halogen-Free PKG) | |
| 4 : Tray (Halogen-Free PKG) | |
| 5 : Tube (Halogen-Free PKG) | |
| 7 : Tape & Reel (Lead-Free PKG) | |
| 8 : Tray (Lead-Free PKG) | |
| 9 : Tube (Lead-Free PKG) | |

MOS Code Information(2/2)

Last Updated : August 2009

<u>S</u>	<u>5</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	-	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>
1	2	3	4	5	6	7	8	9	10	11	12	13	14	15

15. Customer

- 0 : None
- 1 : Bonding Option 1
- 2 : Bonding Option 2
- 3 : Bonding Option 3
- 4 : Bonding Option 4
- 5 : Bonding Option 5
- 6 : Bonding Option 6
- 7 : Bonding Option 7
- 8 : Bonding Option 8
- 9 : Bonding Option 9
- A : Special Marking 1
- B : Special Marking 2
- C : Special Marking 3
- D : Special Marking 4
- E : Special Marking 5
- F : Special Marking 6
- K : Reliability Test
- L : No Logo
- M : No Marking
- N : ANAM Assembly
- Q : Bonding Option 10
- R : Bonding Option 11
- S : Bonding Option 12
- T : Bonding Option 13
- U : Bonding Option 14
- Z : Customer Option

CCD Code Information(1/2)

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S 5 F X X X X X X X - X X X X
 1 2 3 4 5 6 7 8 9 10 11 12 13 14 15

1. System LSI (S)

2. Large Classification : MOS (5)

3. Small Classification

F : CCD

4. Optical Size(inch)

- 3 : 1/3 inch
- 4 : 1/4 inch
- 5 : 1/5 inch
- 6 : 1/6 inch
- 7 : 1/7 inch
- 8 : 1/8 inch
- 9 : 1/9 inch

5~6. # of Pixel

Serial No

7. Method

- F : Frame Redout
- N : NTSC
- P : PAL

8. Version

A~Z

*1st Version → X

9~10. Mask Option

- 02 : B / W Area Sensor with Micro Lense
- 03 : Color Area Sensor
- 04 : Primary Color Area Sensor

11. " - "

12. Package Type

- | | |
|------------|--------------|
| 1 : TEBGA | A : SDIP |
| B : BGA | C : CHIP BIZ |
| D : DIP | E : LQFP |
| G : CLCC | H : LPQ4 |
| J : ELP | K : SBGA |
| L : CERDIP | M : QFP |
| N : COB | P : PLCC |
| Q : QFP | R : TSSOP |
| S : SOP | T : TQFP |
| U : LGA | V : SSOP |
| W : WAFER | Y : FBGA |
| Z : STBGA | |

13. TEST(BIN) Condition

- 0 : None
- A : For the first generation of black and white TEST Condition(BIN1)
- C : For Color Surveillance TEST Condition
- D : For Color Camcorder TEST Condition
- E : For Color PC TEST Condition
- S : B/W Special TEST Condition
- Z : Other

14. Packing

- | | |
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| S : Tape & Reel Reverse | C : Chip Biz |
| D : Chip Biz (3 Inch tray) | |
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| F : Chip Biz (Reverse) | |
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| 7 : Tape & Reel (Lead-Free PKG) | |
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